8M MINI SOM

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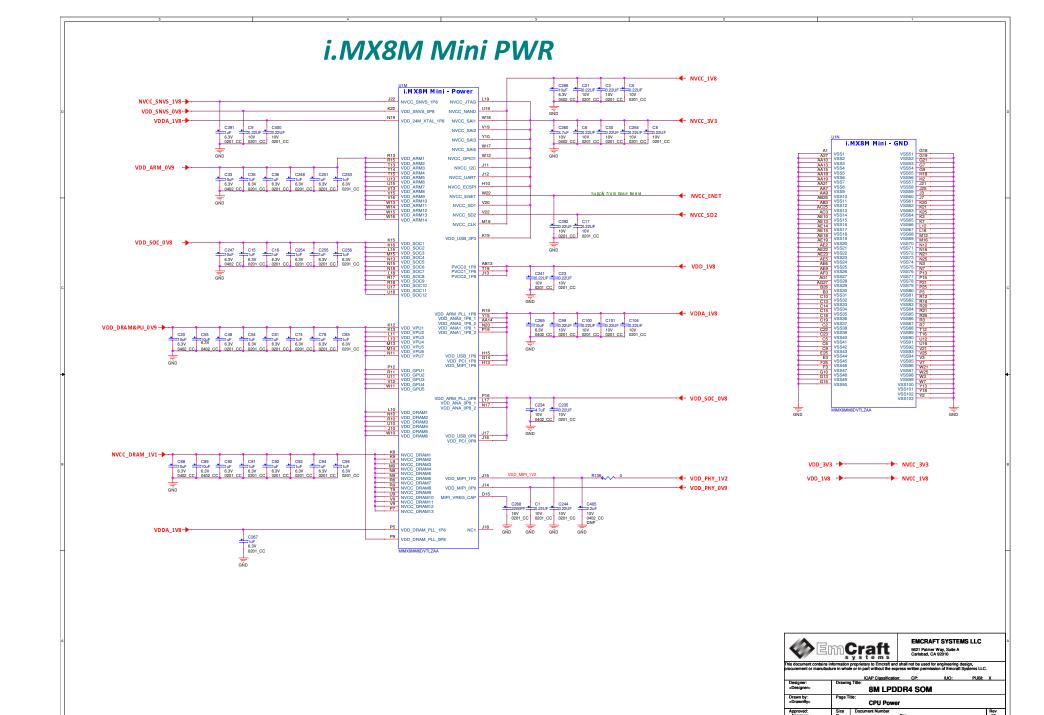
Revision History

Rev. Code	Date	Ву	Description
1A	2019-12-12	AB	Initial version based on SCH-31399 Rev C2
2A	2020-06-15	AB	All the I2C pull-ups were reconnected from 1V8 to 3V3



EMCRAFT SYSTEMS LLC 5621 Palmer Way, Suite A Carlsbad, CA 92010

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Date: Wednesday, June 24, 2020

LPDDR4 2GB Power supply voltage ramp: i.MX8M Mini - DDR J6 PAD/ (LPOSE/TORA/TORA) R6 DRAM_ACOBICAD_A / A12 / A12[BCB] B7 DRAM_ACOBICAD_A / A12 / A12[BCB] B7 DRAM_ACOBICAD_A / A11 / A12[BCB] B7 DRAM_ACOBICAD_A / A11 / A11 B7 DRAM_ACOBICAD_A / A12 / A12 B7 DRAM_ACOBICAD_A / A12 / A13 B7 DRAM_ACOBICAD_A / A13 / A13 C105 C108 C106 C109 10uF 10uF 10uF 10uF 6.3V 6.3V 6.3V 6.3V 6.3V 0402 CC 0402 CC 0402 CC 0402 CC C384 C370 C371 C372 0.22uF 0.22uF 0.22uF 0.22uF 10V 10V 10V 10V 10V 0.201 CC 0.201 CC 0.201 CC 0.201 CC 0.201 CC F4 DRAM_AC00/CKE0_A / CKE0 / CKE0 DRAM_AC01/CKE1_A / CKE1 / CKE1 DMI1_A C10 DRAM_DMI1_B DOS A C11 DRAM DATAGO B DOS A C2 DRAM DATAGO B B DRAM DATAGO NVCC_DRAM_1V1 NVCC DRAM 1V1 X DRAM_AC14/--/A4/A4 K1 VDD2 H12 K3 VDD2 K1 K10 VDD2 K3 K10 VDD2 K10 VDD2 K10 VDD2 K12 VDD2 K12 VDD2 N1 N10 VDD2 N3 N10 VDD2 N3 VDD2 N10 - W6 - W6 - AC4 - AD5 - BRAM_AC28/CA1_B / BA0 / BA0 - BRAM_AC36/CA2_B / A10(AP) / A10(AP) - R5 - BRAM_AC36/CA3_B / A0 / A0 - BRAM_AC36/CA3_B / CA2 / -- BRAM_AC36/CA3_B (AC5) - (A15)/CAS# G2 ODT_CA_A DQ13_A C9 DQ14_A B9 DQ15_A C110 C111 C112 C113 10uF 10uF 10uF 10uF 6.3V 6.3V 6.3V 6.3V 6.3V 0402 CC 0402 CC 0402 CC 0402 CC DMI0_B Y3 DRAM_DMI1_A AB5 DRAM_AC20/CKE0_B/CK_1_B/CK_B DRAM_AC21/CKE1_B/CK_c_B/CK#_B C381 C373 C374 C375 C376 2224F 0.224F 0.224F 0.224F 0.224F 10V 10V 10V 10V 10V 10V 0201 CC 0201 CC 0201 CC 0201 CC 0201 CC P4 | CKE0_B | NC_P5 | NC_N8 | ---DQS0_t_B W3 DRAM_SDQS1_T_A DQS0_c_B X T1 DRAM_AC34/ -- /WE_n(A14)/WE# GND VDDQ B3 VDDQ B5 VDDQ B5 VDDQ B6 VDDQ B1 VDDQ D1 VDDQ D1 VDDQ D1 VDDQ D2 VDDQ D1 VDDQ U1 VDDQ W1 VDDQ W1 VDDQ W1 VDDQ W1 VDDQ W1 VDDQ W1 VDDQ M1 VDDQ M1 VDDQ M1 VDDQ M2 VDDQ A43 VDDQ A410 DMI1_B Y10 DRAM_DMI0_A R2 CA0_B R9 CA1_B R10 CA2_B CA3_B P11 CA4_B CA5_B NVCC_DRAM_1V1 DOB B V11 DRAW DATAS A DO10 B V11 DRAW DATAS A DO11 B DO11 B U11 DRAW DATAS A DO11 B U11 DRAW DATAS A DO11 B U19 DRAW DATAS A NVCC_DRAM_1V1 DO9 B V11 DHAM DATA A DO9 B V11 DHAM DATA A DO10 B D011B US DHAM DATA A D012B V9 DHAM DATA A D013B V9 DHAM DATA A D013B AA9 DHAM DATA A D014B D014B C115 C117 C118 C119 10uF 10uF 10uF 10uF 6.3V 6.3V 6.3V 6.3V 6.3V 0402 CC 0402 CC 0402 CC 0402 CC ODT_CA_B DRAM_DQS2_P DRAM_DQS2_N DRAM_DQS3_P DRAM_DQS3_N DRAM_nRESET R1 RESET_n / RESET_n / RESET# NVCC_DRAM_1V1 C378 C379 C380 C382 C114 0.220F 0.220F 0.220F 0.220F 10V 10V 10V 0201 CC 0201 CC 0201 CC 0201 CC 0201 CC P1 VREF / VREF / VREF DRAM_nRESET __T11 __ RESET_N R7 240 OHM P2 DRAM_ZN R5 240 OHM DRAM_ZQ0 % N2 DRAM_AC19/MTEST / MTEST / MTEST R6 240 OHM DRAM_ZQ1 XG11 NC_G11 MTESDETSMSSDSDS OFS WITH Data Bus Command/Address Pin Name LPDDR4 DDR4 Pin Name LPDDR4 DDR4 RESET_N MTESTI CKEQ_A CKE_A CSQ_A CS_LA CK_LA CK_LA DRAM_CK_T_A DRAM_CK_T_B CADLA CATLA CATLA CATLA CATLA CATLA CATLA DRAM_CK_C_A DRAM_CK_C_B DQU2_A DQU4_A DQU4_A DQU5_A DQU5_A DQU5_A DQU5_A DQU5_L B DQS_L B DML_n_B/DBIL_n_B DQL0_B AB CK_LA CK_CA MTEST CK_LB CK_CB MTEST CKEO B CKE L B CSO B CK L B CK L B CK L B CALB CALB CALB CALB CALB CALB CALB EMCRAFT SYSTEMS LLC **♦**EmCraft 5621 Palmer Way, Suite A Carlsbad, CA 92010 DOS (L.C. 8) DOW (L. 18 / DB) (L.) 18 DOW (L. 18) D 8M LPDDR4 SOM

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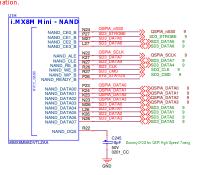
32-bit LPDDR4 Jocument Number <Doc> Date: Wednesday, June 24, 2020

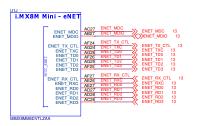


Caution:

IO internal pull up/down is not supported in 3.3V mode, must disable the internal pull up/down via software and use external pull up/down resistors instead.

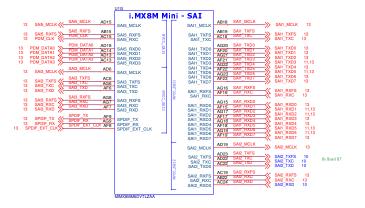
All IO pin groups are impacted except for XTAL, DDR, PCI, USB and MIPI PHY IO's.
See Errata e50080 for detailed information.



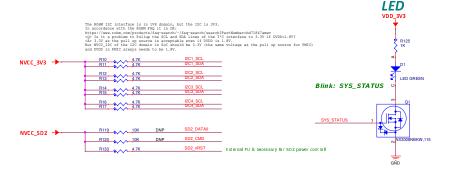






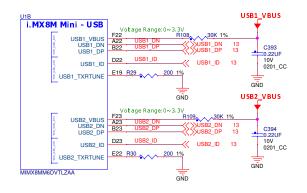


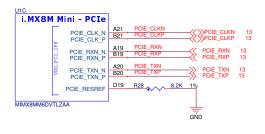




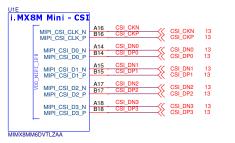
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i.MX8M Mini PHYs

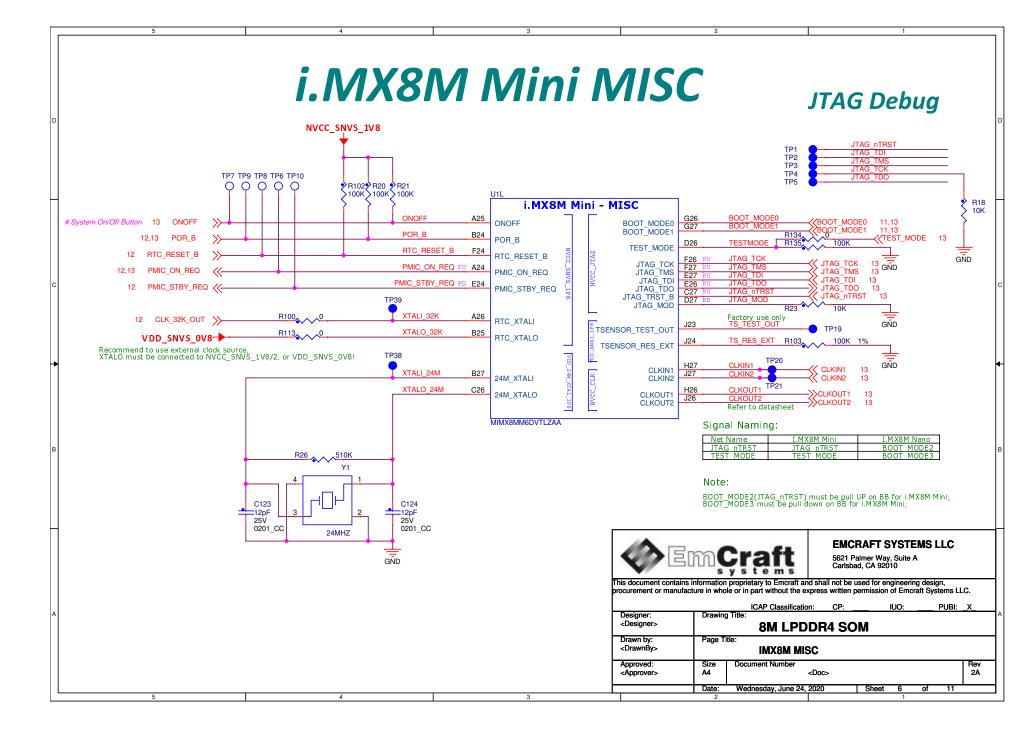


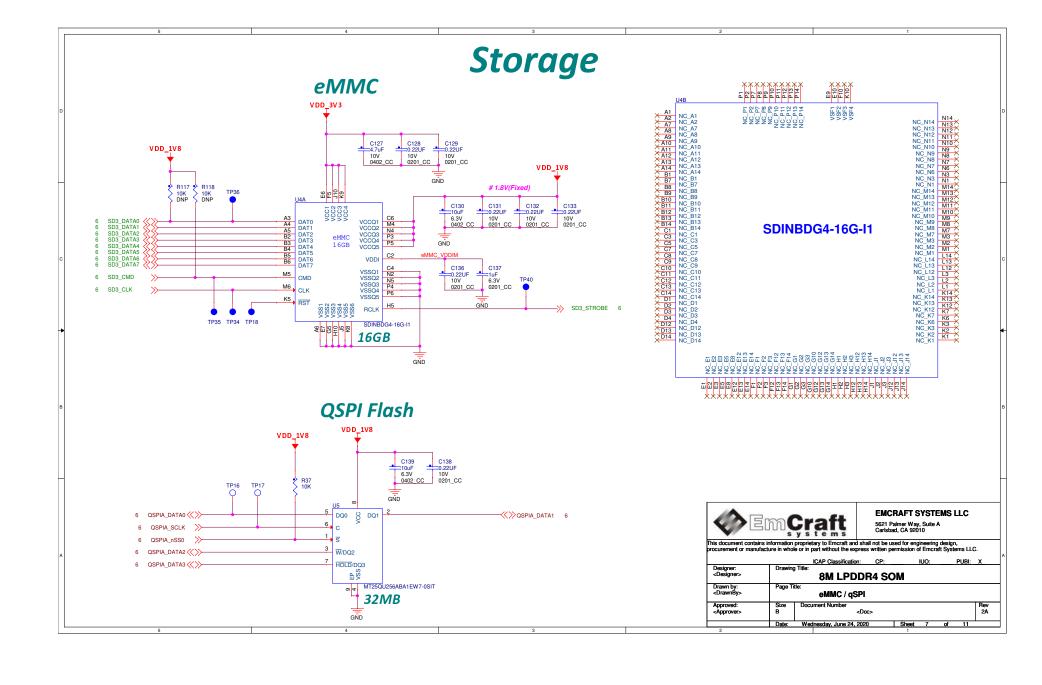


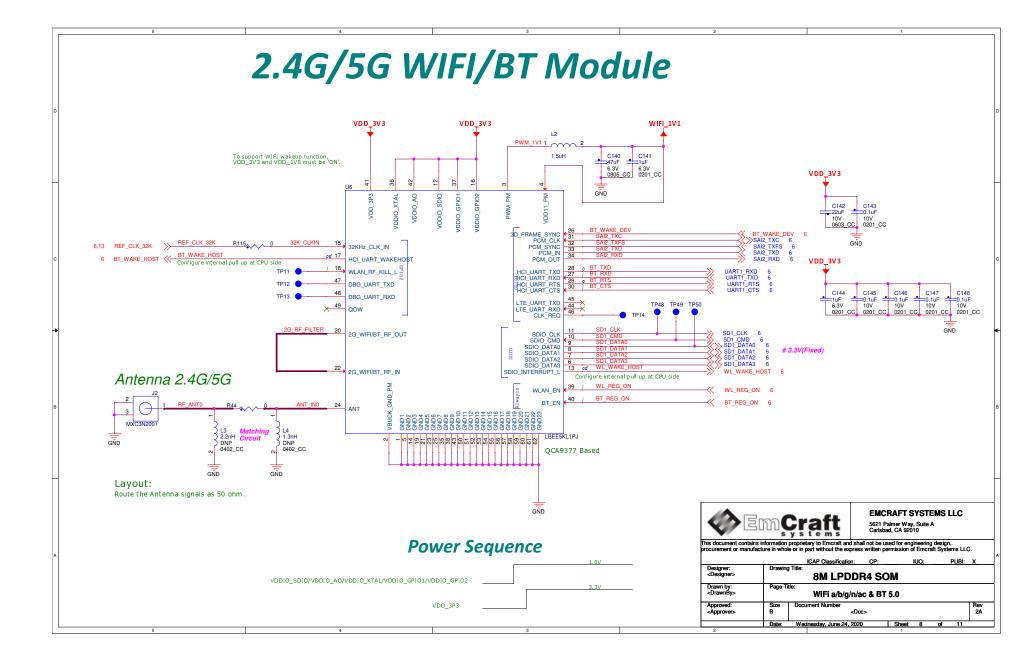












Boot Mode and CFG Switch

Caution

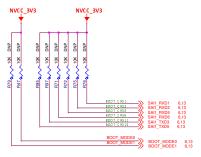
To internal pull up/down is not supported in 3.3V mode, must disable the internal pull up/down via software and use external pull up/down resistors instead.
All IO pin groups are impacted except for XTAL, DDR, PCI, USB and MIPI PHY IO's.
See Errata e50080 for detailed information.

i.MX8M Mini ROM Fuse

	Address	7	6	5	4	3	2	1	0	
	0x470[15:8]	BOOT_CFG[15]	BOOT_CFG[14]	BOOT_CFG[13]	BOOT_CFG[12]	BOOT_CFG[11]	BOOT_CFG[10]	BOOT_CFG[9]	BOOT_CFG[8]	
	0x470[15:8] 0x470[15:8]		001 - SD/eSD			Port S 00 - ul 01 - ul 10 - ul	SDHC1 SDHC2	Power Cycle Enable 'O' - No power cycle '1' - Enabled via	SD Loopback Clock Source Sel (for SDR50 and SDR104 only '0' - through SD pad	
	0x470[15:8]			010 - MM C/eM MC		20 0.	301103		'1' - direct	
	0x470[15:8]	Infinit-Loop (Debug USE only)	011 - NAND Loop g USE only			Pag es In Block: 00 - 128 01 - 64 10 - 32 11 - 256		Nand_Row_address_bytes: 00 - 3 01 - 2 10 - 4 11 - 5		
	0x470[15:8]	0 - Disable 1 - Enable		100 - Q5 Pl		FLAS H_TYPE 000 Device supp 001 Device supp 010 Hyperflash 011 Hyperflash 100 MXIC Oxtal		Device supports 3B read b Device supports 4B read b HyperFlas h 1V8 HyperFlas h 3V3	e supports 3B read by default e supports 4B read by default Flash 1V8 Flash 3V3	
	0x470[15:8]		110 - SPI NOR			Port Select: 000 - eCSPl1 001 - eCSPl2 010 - eCSPl3			SPI Addressing: 0 - 3-bytes (24-bit) 1 - 2-bytes (16-bit)	
	0x470[15:8]		Others - Res	erved for future use						
		BOOT_CFG[7]	BOOT_CFG[6]	BOOT_CFG[5]	BOOT_CFG[4]	BOOT_CFG[3]	BOOT_CFG[2]	BOOT_CFG[1]	BOOT_CFG[0]	
SD/eSD	0x470[7:0]	Fast Boot: O - Regular	Reserved	Res erved	Bus Width: 0 - 1-bit 1 - 4-bit		Speed 000 - Normal/SDR12 001 - High/SDR25 010 - SDR50 011 - SDR104 101 - Reserved for DDR5 Others - Reserved	50	Reserved	
MMC/eMMC	0x470[7:0]	1 - Fast Boot	Bus Width: 000 - 1-bit 001 - 4-bit 010 - 8-bit 110 - 8-bit DDR (MMC 4.4) 110 - 8-bit DDR (MMC 4.4) EBe - reserved.		Speed 00 - Norm 01 - High 10 - Res er 11 - Res er	ved for HS 200	USDHC IO VOLTAGE SELE CTION For Normal Boot Mode 0 - 3.3V 1 - 1.8V	USDHC IOV OLTAGE SELECTION For Manufacture Mode 0 - 3.3V 1 - 1.8V		
NAND	0x470[7:0]	BT_TOG GLEMODE	BOOT_SE# 00-2 01-2 10-4 11-8	RCH_COUNT:		Toggle Mode 33M Hz Pre 000'- 16 GPMICLK cycle 001'- 1 GPMICLK cycle 010'- 2 GPMICLK cycle 011'- 3 GPMICLK cycle 100'- 4 GPMICLK cycle 100'- 5 GPMICLK cycle 110'- 6 GPMICLK cycle 1111'- 7 GPMICLK cycle 1111'- 15 GPMICLK cycle		cy:	R es e rved	
FlexSPI	0x470[7:0]	HOLD 00 - 5: 01 - 1 10 - 3 11 - 1:	00 us ms ms	FLAS H Auto Pro Ty pe	be		FlexSPI FLASH	Dummy Cycle		
SPINOR	0x470[7:0]	CS select SPI only: 00 - CS#0 default 01 - CS#1 10 - CS#2 11 - CS#3	Reserved	Reserved	Res erve d	Res erve d	Res erve d	Res erve d	Reserved	

BT_CFG Pins:

SAI1_RXDO BOOT_CFG0 SAI1_RXD1 BOOT_CFG1 SAI1_RXD2 BOOT_CFG2 SAI1_RXD3 BOOT_CFG3 SAI1_RXD4 BOOT_CFG4 SAI1_RXD5 BOOT_CFG5 SAI1_RXD6 BOOT_CFG6 SAI1_RXD7 BOOT_CFG7 SAI1 RXD8 BOOT_CFG8 SAI1_RXD9 BOOT_CFG9 SAI1_RXD10 BOOT_CFG10 SAI1_RXD11 BOOT_CFG11 SAI1_RXD12 BOOT_CFG12 SAI1_RXD13 BOOT_CFG13 SAI1_RXD14 BOOT_CFG14 SAI1_RXD15 BOOT_CFG15



Note:

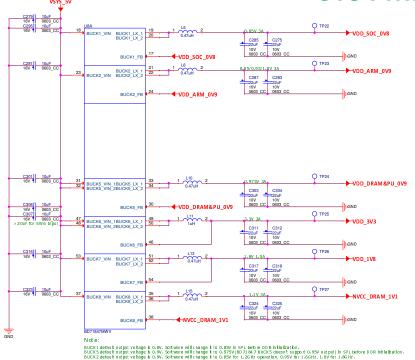
- t . Boo tcfg/SAI1 singals have internal PD before and after POR_B reset is deasserted
- 2. Standalone S OM board can support eMMC/SDHC3 boot, by populating R71, R72, R75, R76, R79, R95, R97!
- 3 . When using Base Board for Multi boot selection , you must keep the resistors DNP on SOM board!

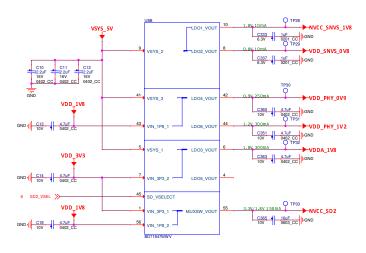
Boot Mode

ВО	OT_MODE1	BOOT_MODE0
во	OT TYPE:	
00	Boot From F	uses
01	Serial Down	loader
10	Internal Boo	ot (Development)
11	Reserved	

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SYS PMIC





GND Testpoints



NVCC_SNVS_1V8 TPs2
NTLDO_IV5 C273 II 1uF Itempo
TP53
6 BC1_SCL >> R54 + \lambda \ 9 Z5 SCL & SC
CPU WDOG B Resert 6 WDOG B RESERVE 100K PRODE WDOG B PR
8,13 PMIC_ON_REQ >> R51
8 PMC_STBY_REQ D 16 PMIC_STBY_REQ
NVCC_SNVS_1V8 R81 100K R127 40 PWRON RTC_RESET_B 8
XN 32X 14 XIN 0 0 0 888 8 50 8 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6 6
DNP 8071847MWV b 21 5/8/8/5
C299 58.75804.2 C299 50V 50V
0201_CC

1. PWRON Is used as RESET Button as default, need to configure PWRO II bing push as 10ms, Cold Reset, and short push detect should be disabled!

2. WDDG B is used as Cold Reset, external pull up is needed, On EVK. R106 is not necessary, since WDDG B/GP/D1 1002 of CPU has internal pull up.

i.MX8M Mini LPDDR4 EVK Power Sequence								
SEQ	PWR/Signal	REG	MIN	ТҮР	MAX	Max Current(mA)		
1 2 3 4 5 6 6 7 7 8 9 10 10 11 12	NVCC_SNVS_1V8 VDD_SNVS_0V8 RTC_RESET_B CLK_32K_OUT VDD_SOC_0V8 VDD_DRAM&PU_0V9 VDD_PHY_0V9 VDD_ARM_0V9 VDDA_1V8 VDD_IV8/NVCC_1V8 NVCC_DRAM_1V1 VDD_3V3/NVCC_3V3 NVCC_SD2 VDD_PHY_1V2 POR_B	LDO1 LDO2 RTC_RESET_B RTC_CLK BUCK1 BUCK5 LDO4 BUCK2 LDO3 BUCK7 BUCK8 BUCK6 MUXSW LDO6 POR_B	1.62 0.76 0.78/0.805 0.805/0.855 0.805/0.9/0.95 1.71 1.65 1.06 3 3.0/1.65 1.14	1.8 0.8 0.82/0.85 0.85/0.95 0.9 0.85/0.95/1.0 1.8 1.1 3.3 3.3/1.8 1.2	1.98 0.9 0.9 0.9/1.0 1.0 0.95/1.0/1.05 1.89 1.95 1.14 3.6 3.6/1.95 1.26	10 10 3000 3000 250 3000 3000 1500 3000 3000 150 3000		

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